

IN THE CLAIMS

Claims 1-39: Canceled.

40. (Previously Presented) An electronic component, comprising:
- a candidate substrate; and
- a candidate polymer, wherein the candidate polymer comprises a high adhesive strain component with respect to the candidate substrate;
- wherein the candidate substrate and the candidate polymer are coupled to one another to form an interface, and wherein the substrate and the polymer are selected as candidates based on a software program.
41. (Previously Presented) The electronic component of claim 40, wherein the software program comprises strain cycling data.
42. (Previously Presented) The electronic component of claim 40, wherein the software program evaluates at least one property of the interface, including size, shape and bond geometry.
43. Canceled.
44. (Previously Presented) The electronic component of claim 40, wherein the candidate polymer comprises at least one of the following chemical precursors: tris(2,3-epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H) trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and bis(3,4-epoxycyclohexylmethyl)adipate.
45. (Previously Presented) The electronic component of claim 40, wherein the candidate polymer is amorphous, crosslinked, crystalline or branched.
46. (Previously Presented) The electronic component of claim 45, wherein the candidate

polymer is crosslinked.

47. Canceled.
48. (Previously Presented) The electronic component of claim 42, wherein software program evaluates at least one of the following: a set of modeling data, a set of durability data or a set of evaluation data.
49. (Currently Amended) An electronic component, comprising:

a candidate substrate;

a candidate first polymer; and

a candidate second polymer, wherein the candidate first polymer comprises a high adhesive strain component with respect to the candidate substrate and the candidate second polymer and wherein the candidate second polymer comprises a high adhesive strain component with respect to the candidate first polymer;

wherein ~~the candidate substrate~~, the candidate first polymer and the candidate second polymer are coupled to one another to form an interface, and wherein first polymer and the second polymer are selected as candidates based on a software program, and wherein one of the candidate first polymer or the candidate second polymer is coupled to the candidate substrate.
50. (Previously Presented) The electronic component of claim 49, wherein the software program comprises strain cycling data.
51. (Previously Presented) The electronic component of claim 49, wherein the software program evaluates at least one property of the interface, including size, shape and bond geometry.
52. Canceled.
53. (Previously Presented) The electronic component of claim 49, wherein at least one of the

candidate first polymer or the second candidate polymer comprises at least one of the following chemical precursors: tris(2,3-epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H) trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and bis(3,4-epoxycyclohexylmethyl)adipate.

54. (Previously Presented) The electronic component of claim 49, wherein at least one of the first candidate polymer or the second candidate polymer is amorphous, crosslinked, crystalline or branched.
55. (Previously Presented) The electronic component of claim 53, wherein at least one of the first candidate polymer or the second candidate polymer is crosslinked.
56. (Previously Presented) The electronic component of one of claims 41 or 50, wherein the high adhesive strain component is determined by the software program.
57. (Previously Presented) The electronic component of one of claims 41 or 50, wherein the software program determines strain intercept.